

Diffusion bonding of Al 6061 and Cu by hot isostatic pressing

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In this work, diffusion bonding between Aluminum and Copper were successfully performed by hot isostatic pressing (HIP). In order to improve the strength of diffusion bonding joint, different thickness of pure Nickel foils was used as an intermediate layer. The microstructure of the interface between Aluminum and Copper was investigated using X-ray diffraction (XRD) technique, secondary electron microscopy (SEM), and the mechanical property evaluated through nanoindentation test.

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